

31 - making a microrelief for each microcomponent by mechanical machining of the substrate, the mechanical machining comprising moving at least one tool translationally and parallel to the substrate; and

- cutting out the microcomponents in the substrate such that individual microcomponents or groups of microcomponents are separated from each other.

sub 2 16. (Amended) A method according to Claim 14, wherein making a microrelief is performed to an extent of obtaining optical quality of the microrelief. 112

32 17. (Amended) A method according to Claim 14, wherein the microrelief is made with a single tool moved at the surface of the substrate.

33 18. (Amended) A method according to Claim 14, wherein the microrelief is made by several tools working simultaneously and/or in succession.

34 20. (Amended) A method according to Claim 14, wherein the microcomponents are microprisms.

sub 3 21. (Amended) A method according to Claim 14, wherein the microprisms are made by a "V" profile abrasive blade.

Add new Claims 22- as follows:

35 22. (New) A method according to Claim 19, the saw having a blade with plane and parallel faces, or having at least an inclined face.

36 23. (New) A method according to Claim 14, wherein making a microrelief consists of passing a blade having a die which does not have abrasive grit therein, said